TLC69635-Q1 汽车 100mA、24 通道 LED 驱动器，配备集成振荡器和高级诊断功能

1 特性

- 符合面向汽车应用的 AEC-Q100 标准
  - 1 级：–40°C 至 125°C 环境工作温度范围
  - 器件 HBM 分类等级 H1C
  - 器件 CDM 分类等级 C4B
- 以符合功能安全标准为目标
  - 专为功能安全应用开发
  - 有助于使 ISO 26262 系统设计满足 ASIL-B 要求的文档
- 24 个集成的电流吸收器
  - 可编程的 16 位 PWM/混合调光
  - 可编程的 7 位模拟点校正 (DC)
  - 最大输出电流/电压：100mA/16V
- 集成的 33MHz 振荡器
  - 500Hz 的 16 位 PWM 输出
  - 采用增强频谱 (ES) PWM 时，刷新率大于 20KHz
- 高速通信
  - 串行外设接口 (SPI)
  - 数据速率高达 17Mbps
- 电源效率优化
  - 自适应余量电压控制 (AHVC)
  - 器件节电模式 (PSM)
- 降低 EMI
  - 接口：可编程缓冲器驱动能力
  - 电流吸收器：相移/展频
- 保护和诊断
  - LED：开路/短路检测/运行状况检查
  - 电流吸收器：相邻引脚短路/运行状况检查
  - 接口：CRC/命令错误/超时错误/通信看门狗
  - 器件：欠压/ISET 超出范围/热关断/存储器 CRC/OTP CRC/OSC 看门狗

2 应用

- 汽车中心信息显示屏
- 汽车仪表组显示屏
- 汽车抬头显示

3 说明

TLC69635-Q1 是一款 LED 驱动器，它具有 24 条恒定电流吸收器通道，可提供高达 16 位的独立像素级 LED PWM 控制。每条通道还实施额外的 7 位点校正 (DC) 以控制峰值电流。每个器件通过串行外设接口 (SPI) 共享数据流，其最多支持 511 个器件的连接。该接口与同一组中的 LED 驱动器软件兼容，可根据 LED 电流和 LED 总数应用于不同的应用场景。

为了优化整体系统电源效率，该器件配备了自适应余量电压控制 (AHVC) 方案，用于优化每条通道和每个器件的余量电压。只需要将菊花链最后一个器件的 OUT23 引脚编程为 FB 引脚，即可优化来自 DC/DC 的 LED 电源电压。

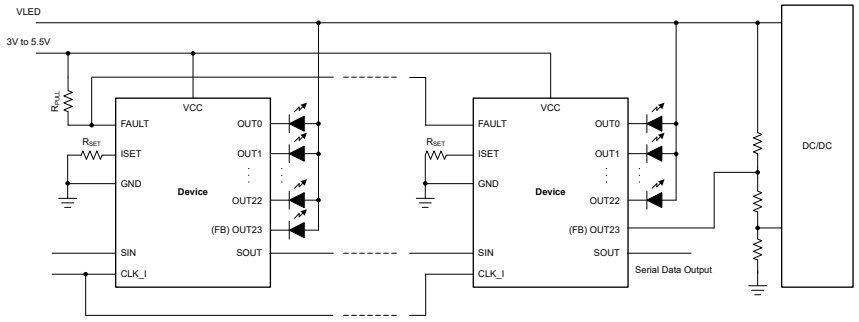
TLC69635-Q1 配备了 LED、电流吸收器、通信和器件的诊断功能。

器件信息

器件型号	封装(1)	封装尺寸(2)
TLC69635-Q1	WQFN (32) 可湿性侧面	4mm × 4mm
	HTSSOP (32)	11mm × 6.1mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。

(2) 封装尺寸（长 × 宽）为标称值，并包括引脚（如适用）。



简化版原理图

本资源的原文使用英文撰写。 为方便起见，TI 提供了译文；由于翻译过程中可能使用了自动化工具，TI 不保证译文的准确性。 为确认准确性，请务必访问 ti.com 参考最新的英文版本（控制文档）。

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4 器件比较

器件型号	通道编号	最大值通道电流	功能安全分类	接口	软件兼容
TLC69621-Q1	8	60mA	功能安全型	SPI	组 1
TLC69624-Q1	24				
TLC69627-Q1	48				
TLC69631-Q1	8	100mA			
TLC69634-Q1	24				
TLC69637-Q1	48				
TLC69622-Q1	8	60mA	符合功能安全标准	SPI	组 2
TLC69625-Q1	24				
TLC69628-Q1	48				
TLC69632-Q1	8	100mA			
TLC69635-Q1	24				
TLC69638-Q1	48				
TLC69623-Q1	8	60mA	符合功能安全标准	CSI	组 3
TLC69626-Q1	24				
TLC69629-Q1	48				
TLC69633-Q1	8	100mA			
TLC69636-Q1	24				
TLC69639-Q1	48				

5 修订历史记录

注：以前版本的页码可能与当前版本的页码不同

日期	修订版本	注释
2026 年 7 月	*	初始发行版

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6 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是指定器件可用的最新数据。数据如有变更，恕不另行通知，且不会对此文档进行修订。有关此数据表的浏览器版本，请查阅左侧的导航栏。

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封装选项附录

封装信息

可订购器件型号	状态 (1)	材料类型 (2)	封装 | 引脚	包装数量 | 包装	RoHS (3)	引脚镀层/焊球材料 (4)	MSL 等级/回流焊峰值温度 (5)	工作温度 (°C)	器件标识 (6)
TLC69635QDAPRQ1	有效	量产	HTSSOP (DAP) | 32	2500 | LARGE T&R	是	NIPDAU	Level-2-260C-168 HR	-40 至 125	TLC69635Q1
TLC69635QRSNRQ1	有效	量产	WQFN (RSN) | 32	5000 | LARGE T&R	是	SN	Level-1-260C-UNLIM	-40 至 125	69635Q1

(1) **状态：**有关状态的详细信息，请参阅我们的 产品生命周期。
(2) **材料类型：**指定时，预量产器件是原型/试验器件，尚未获批或发布以进行全面生产。测试和最终工艺（包括但不限于质量保证、可靠性测试以及/或工艺鉴定）可能尚未完成，并且本器件可能会进一步更改，也可能中断研发。即使可供订购，所购器件仍将可能在结算时被取消，并且所购器件仅可用于早期内部评估。这些器件一经售出，概不提供任何保修。
(3) **RoHS 值：**是、否、RoHS 豁免。有关更多信息和值定义，请参阅“ TI RoHS 声明 ”。
(4) **引脚镀层/焊球材料：**器件可能有多种材料镀层选项。各镀层选项用垂直线隔开。如果铅镀层/焊球值超出最大列宽，则会折为两行。
(5) **MSL 等级/回流焊峰值温度：**湿敏等级等级和峰值焊接（回流焊）温度。如果器件具有多个湿敏等级，则仅显示符合 JEDEC 标准的最低等级。有关将器件安装到印刷电路板上时采用的实际回流焊温度，请参阅装运标签。
(6) **器件标识：**器件上可能还有与徽标、批次跟踪代码信息或环境分类相关的其他标识。
如有多个器件标识，将用括号括起来。不过，器件上仅显示括号中以“~”隔开的其中一个器件标识。如果某一行缩进，说明该行续接上一行，这两行合在一起表示该器件的完整器件标识。

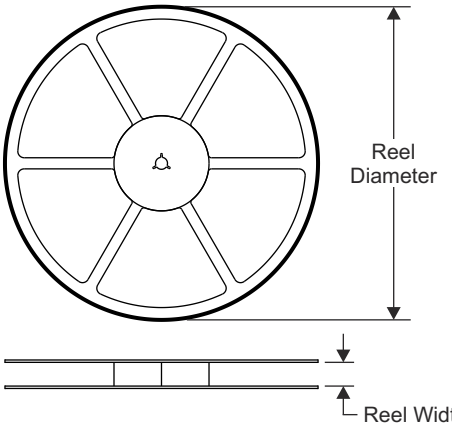
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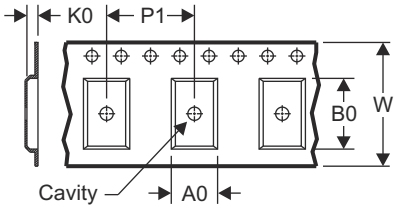
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6.1 卷带包装信息

REEL DIMENSIONS

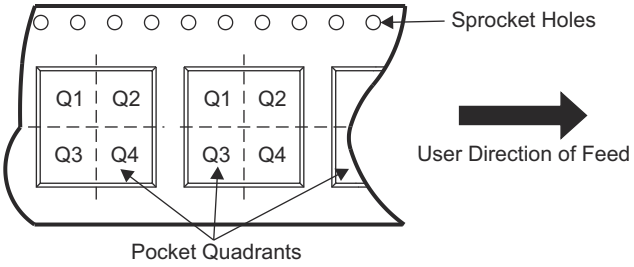


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

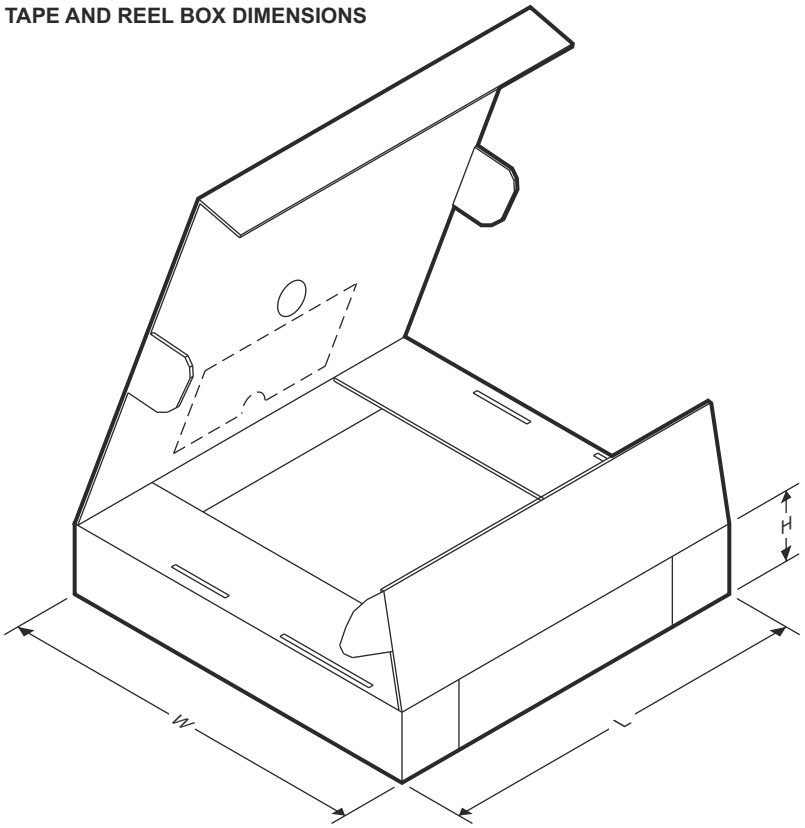
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



器件	封装类型	封装图	引脚	SPQ	卷带直径 (mm)	卷带宽度 W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1象限
TLC69635QDAPRQ1	HTSSOP	DAP	32	2500	330	24.4	8.8	11.8	1.8	12	24	Q1
TLC69635QRSNRQ1	WQFN	RSN	32	5000	330	12.4	4.25	4.25	1.15	8	12	Q2

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TAPE AND REEL BOX DIMENSIONS



器件	封装类型	封装图	引脚	SPQ	长度 (mm)	宽度 (mm)	高度 (mm)
TLC69635QDAPRQ1	HTSSOP	DAP	32	2500	356	356	45
TLC69635QRSNRQ1	WQFN	RSN	32	5000	367	367	35

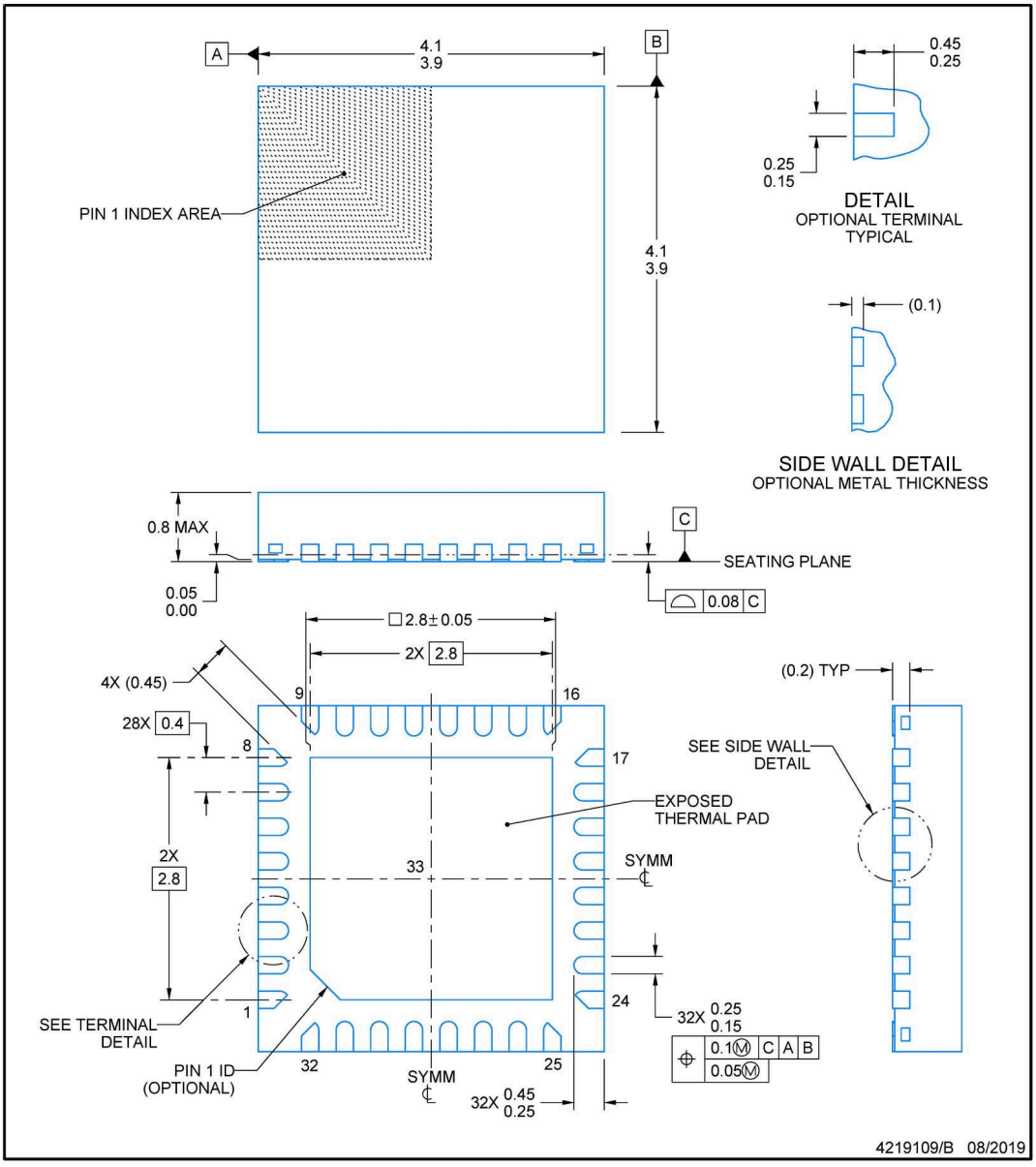
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PACKAGE OUTLINE

RSN0032B

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

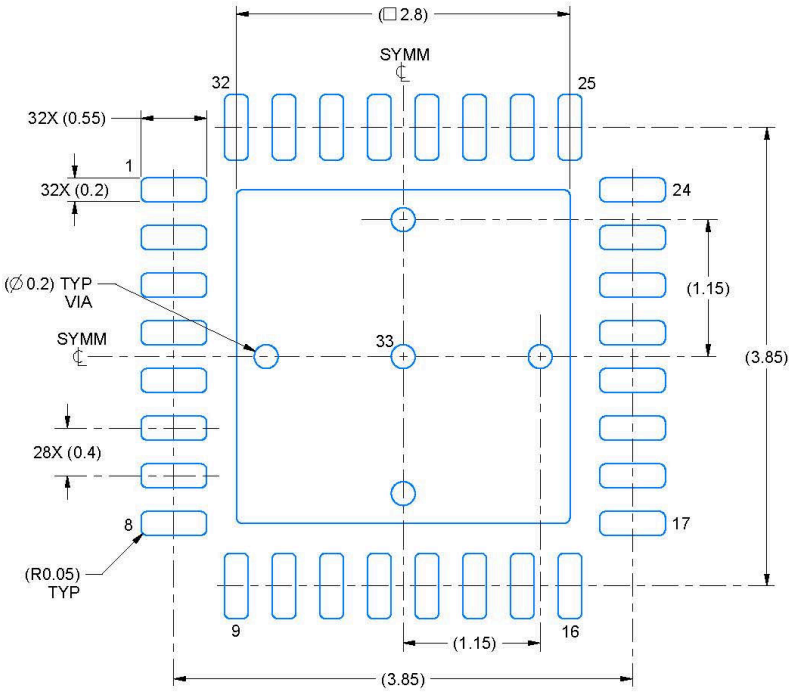
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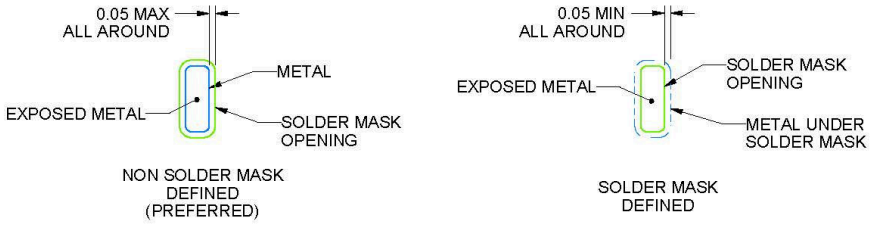
EXAMPLE BOARD LAYOUT

RSN0032B — **WQFN - 0.8 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:20X



SOLDER MASK DETAILS

4219109/B 08/2019

NOTES: (continued)

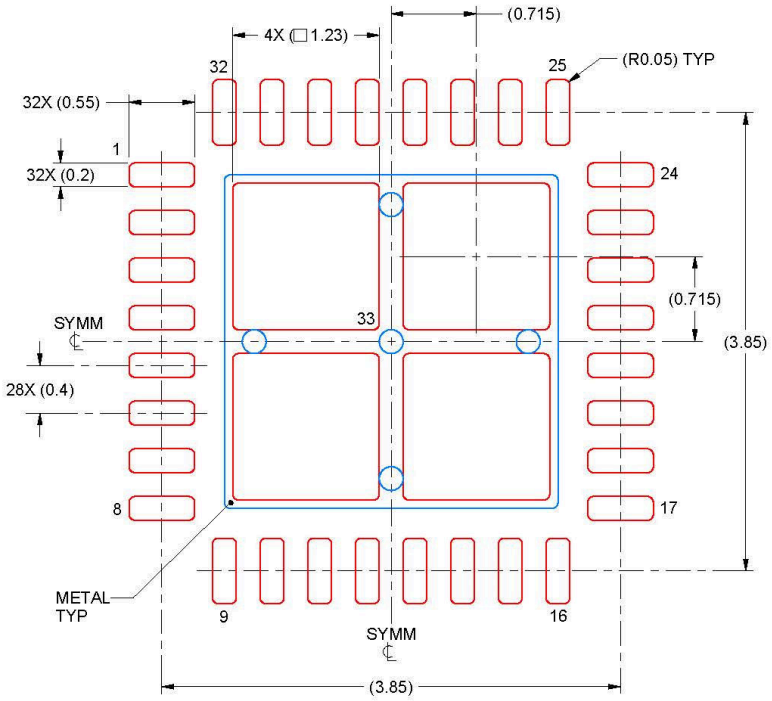
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

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EXAMPLE STENCIL DESIGN

RSN0032B — **WQFN - 0.8 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL

EXPOSED PAD 33:
77% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:20X

4219109/B 08/2019

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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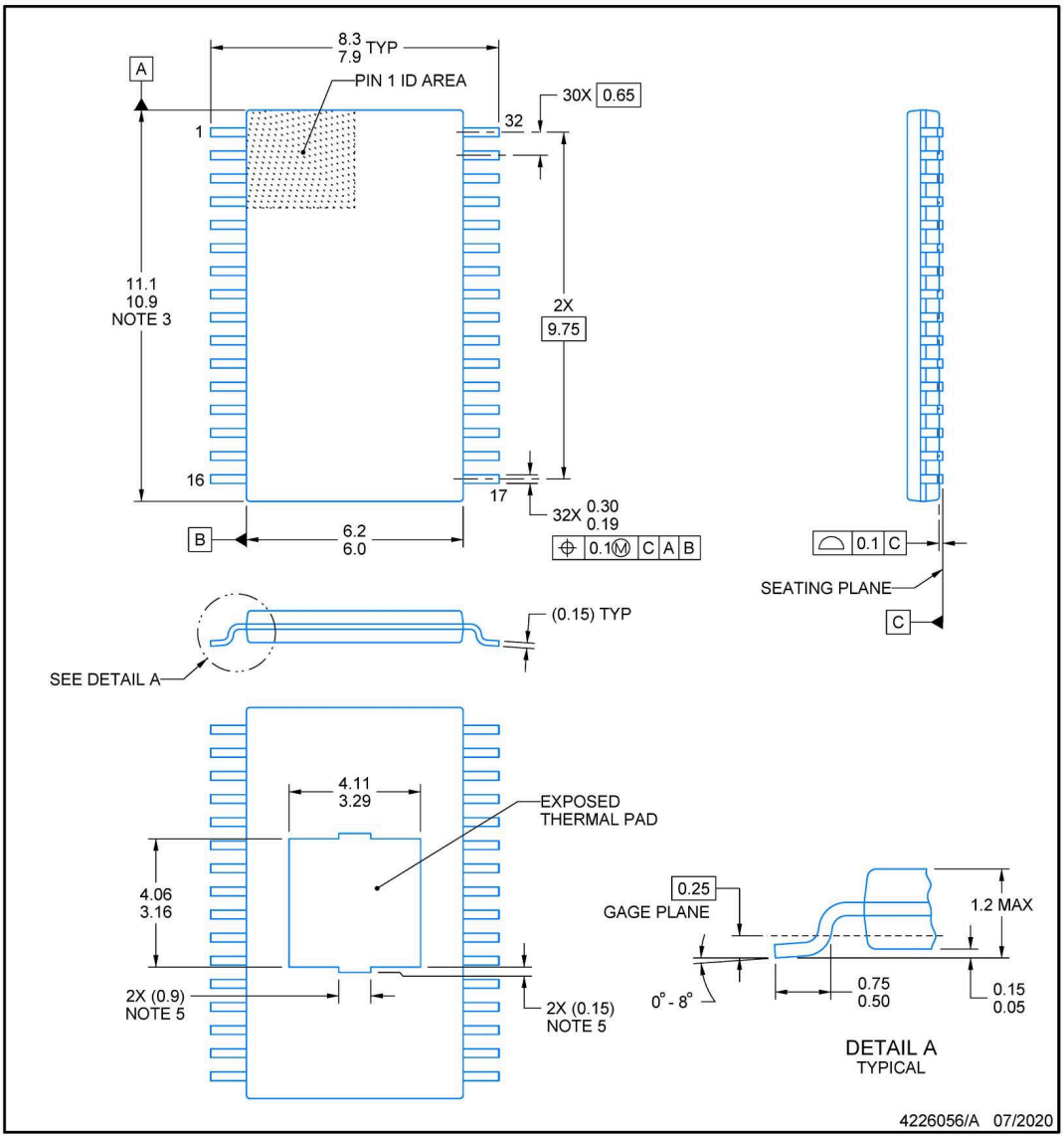
PACKAGE OUTLINE

DAP0032F



PowerPAD™ TSSOP - 1.2 mm max height

PLASTIC SMALL OUTLINE



PowerPAD is a trademark of Texas Instruments.

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.
5. Features may differ and may not be present.

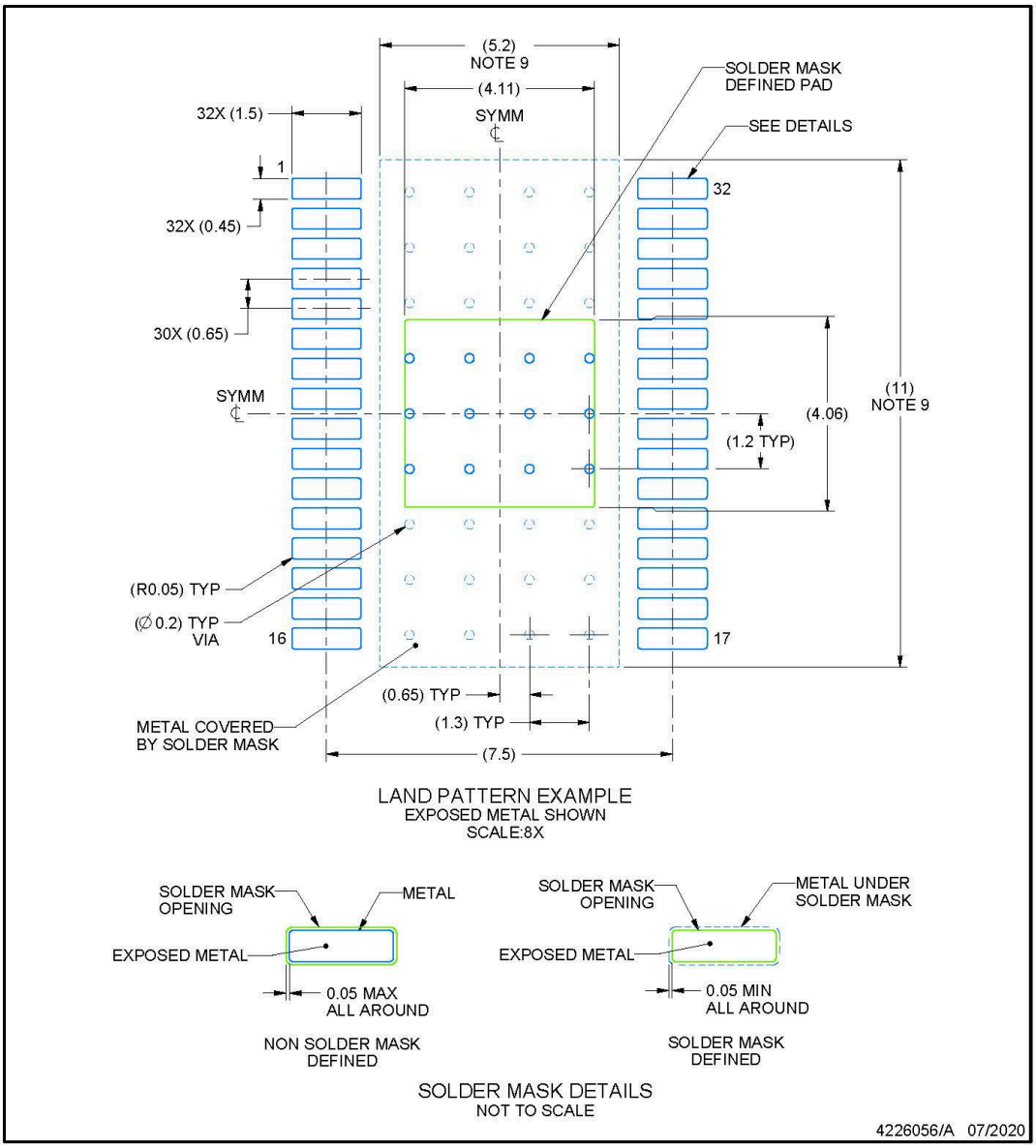
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EXAMPLE BOARD LAYOUT

DAP0032F — **PowerPAD™ TSSOP - 1.2 mm max height**

PLASTIC SMALL OUTLINE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Size of metal pad may vary due to creepage requirement.

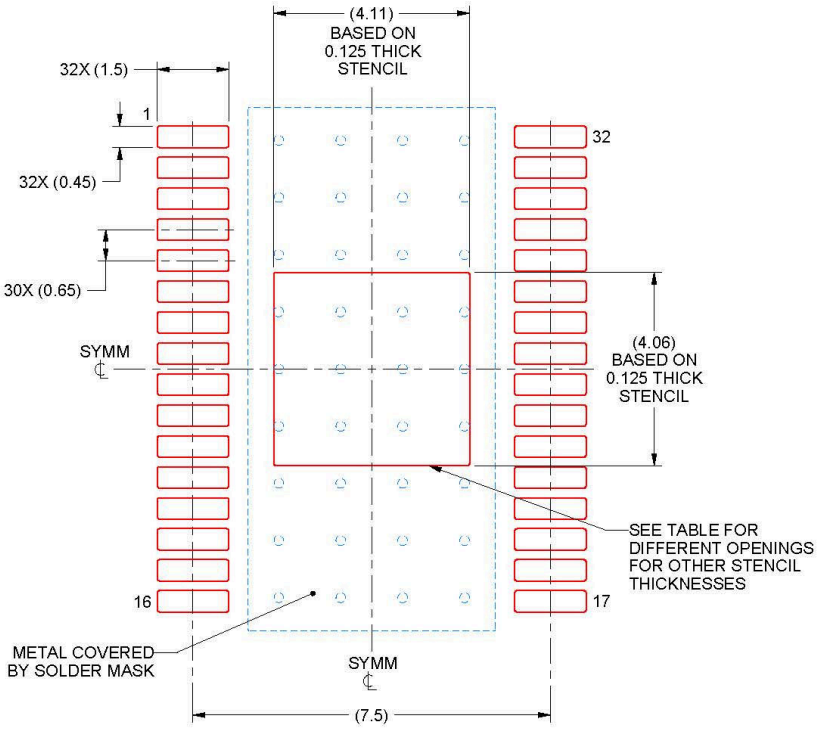
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EXAMPLE STENCIL DESIGN

DAP0032F — **PowerPAD™ TSSOP - 1.2 mm max height**

PLASTIC SMALL OUTLINE



SOLDER PASTE EXAMPLE
EXPOSED PAD
100% PRINTED SOLDER COVERAGE BY AREA
SCALE:8X

STENCIL THICKNESS	SOLDER STENCIL OPENING
0.1	4.60 X 4.54
0.125	4.11 X 4.06 (SHOWN)
0.15	3.75 X 3.71
0.175	3.47 X 3.43

4226056/A 07/2020

NOTES: (continued)

10. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
11. Board assembly site may have different recommendations for stencil design.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TLC69635QDAPRQ1	Active	Production	HTSSOP (DAP) | 32	2500 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-	TLC69635Q1
TLC69635QRSNRQ1	Active	Production	QFN (RSN) | 32	5000 | LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-	69635Q1

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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GENERIC PACKAGE VIEW

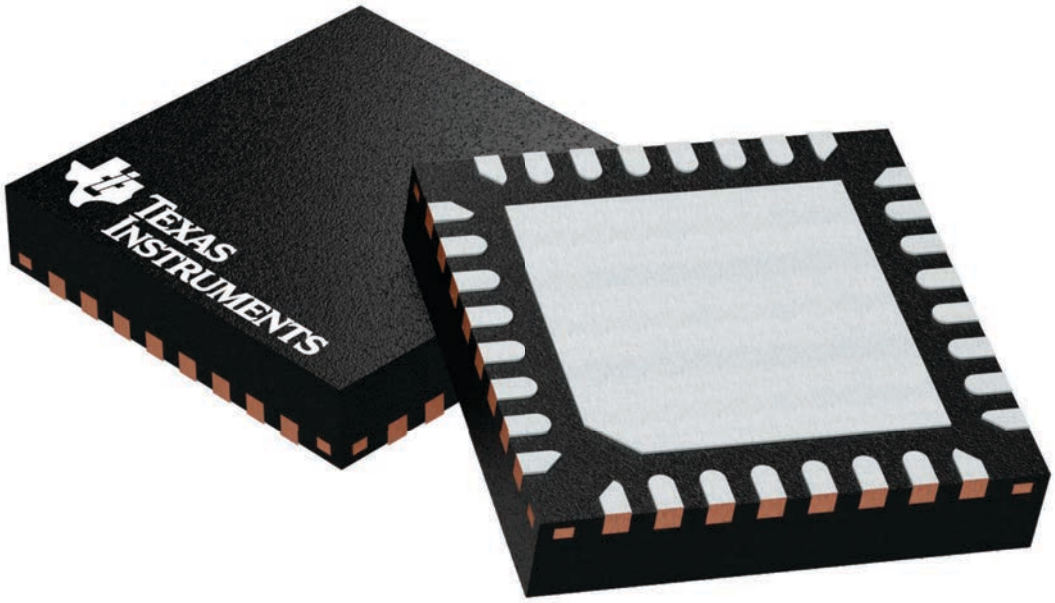
RSN 32

WQFN - 0.8 mm max height

4 x 4, 0.4 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



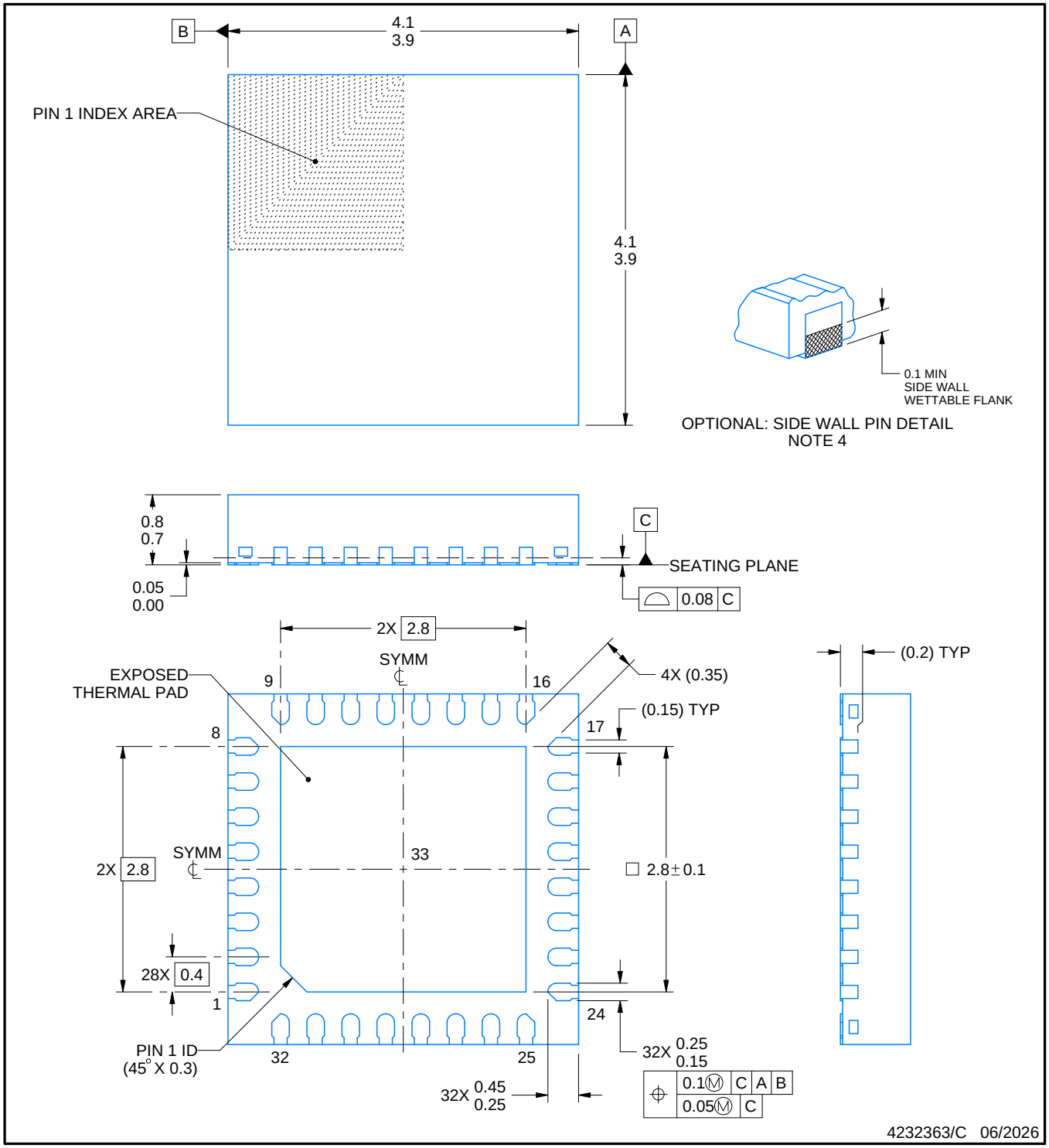
4225265/A

PACKAGE OUTLINE

RSN0032D

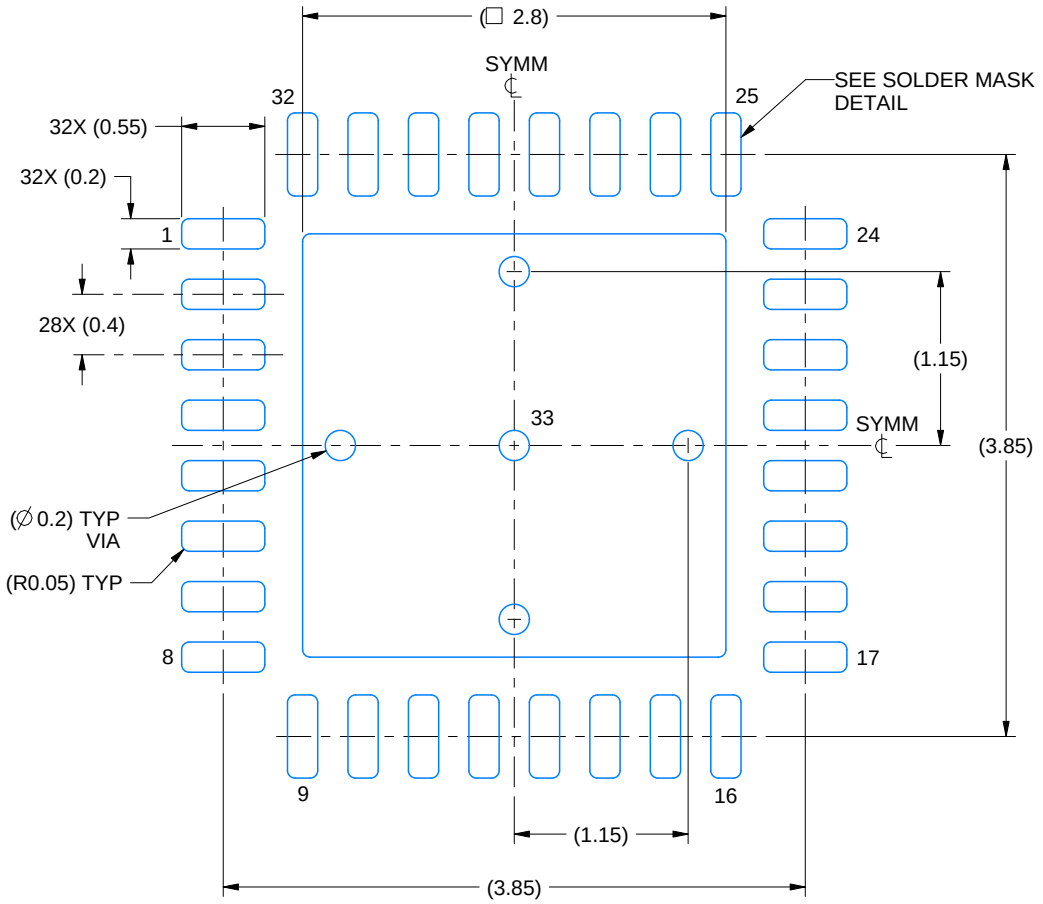
WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

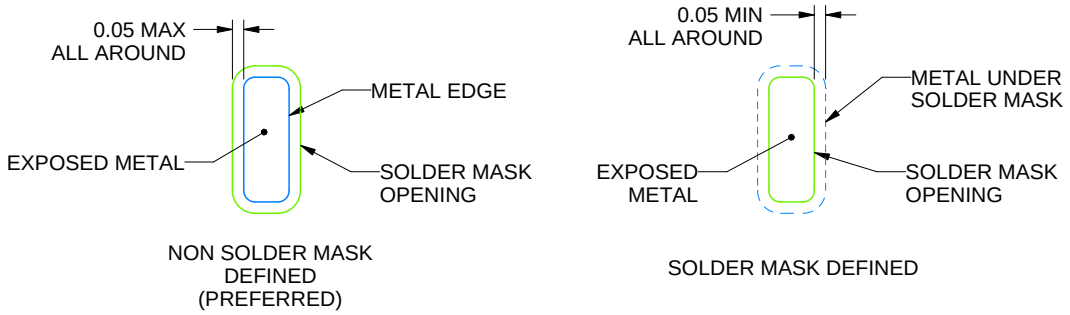


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.
4. Minimum 0.1 mm solder wetting on pin side wall. Available for wettable flank version only.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X



SOLDER MASK DETAILS

4232363/C 06/2026

NOTES: (continued)

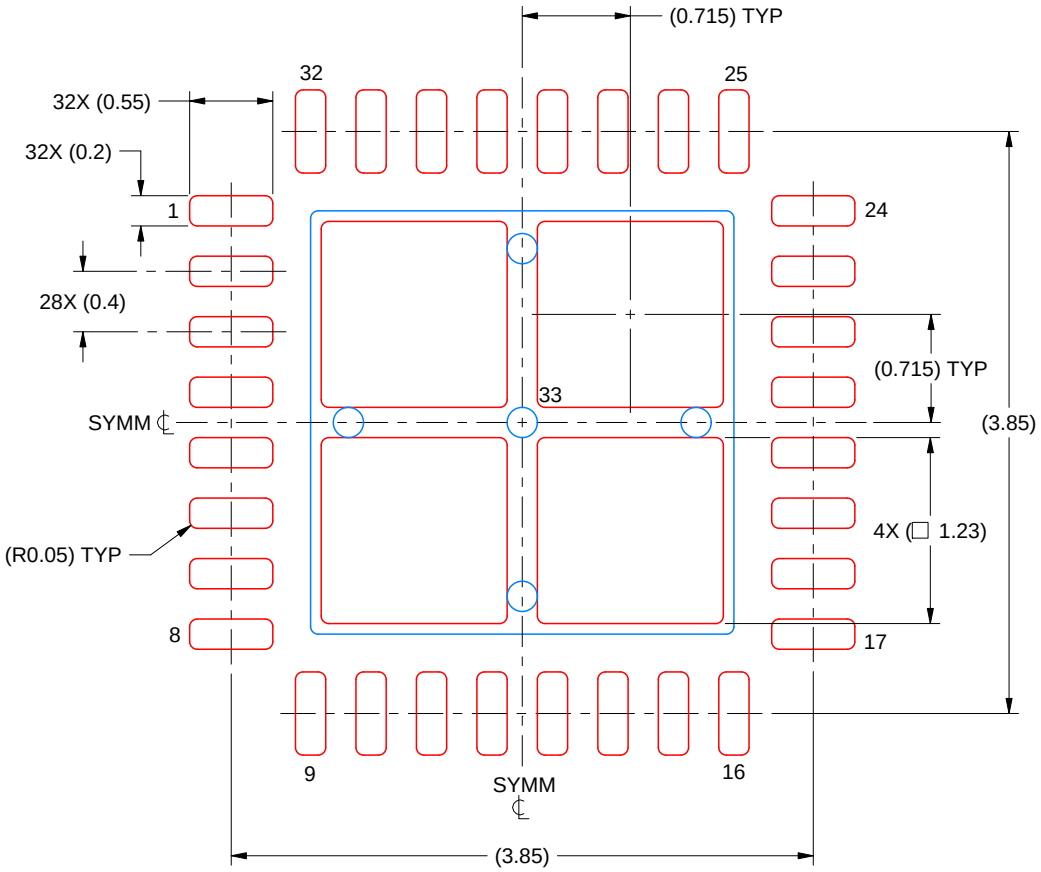
5. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
6. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

RSN0032D

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.1 MM THICK STENCIL
SCALE: 20X

EXPOSED PAD 33
77% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

4232363/C 06/2026

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

GENERIC PACKAGE VIEW

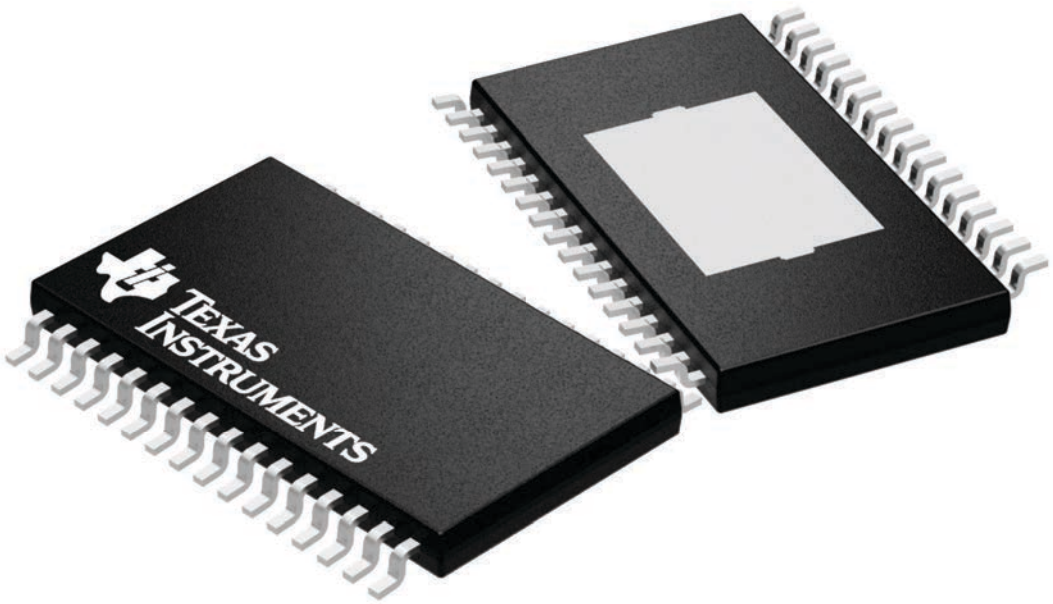
DAP 32

PowerPAD™ TSSOP - 1.2 mm max height

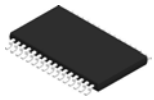
8.1 x 11, 0.65 mm pitch

PLASTIC SMALL OUTLINE

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4225303/A

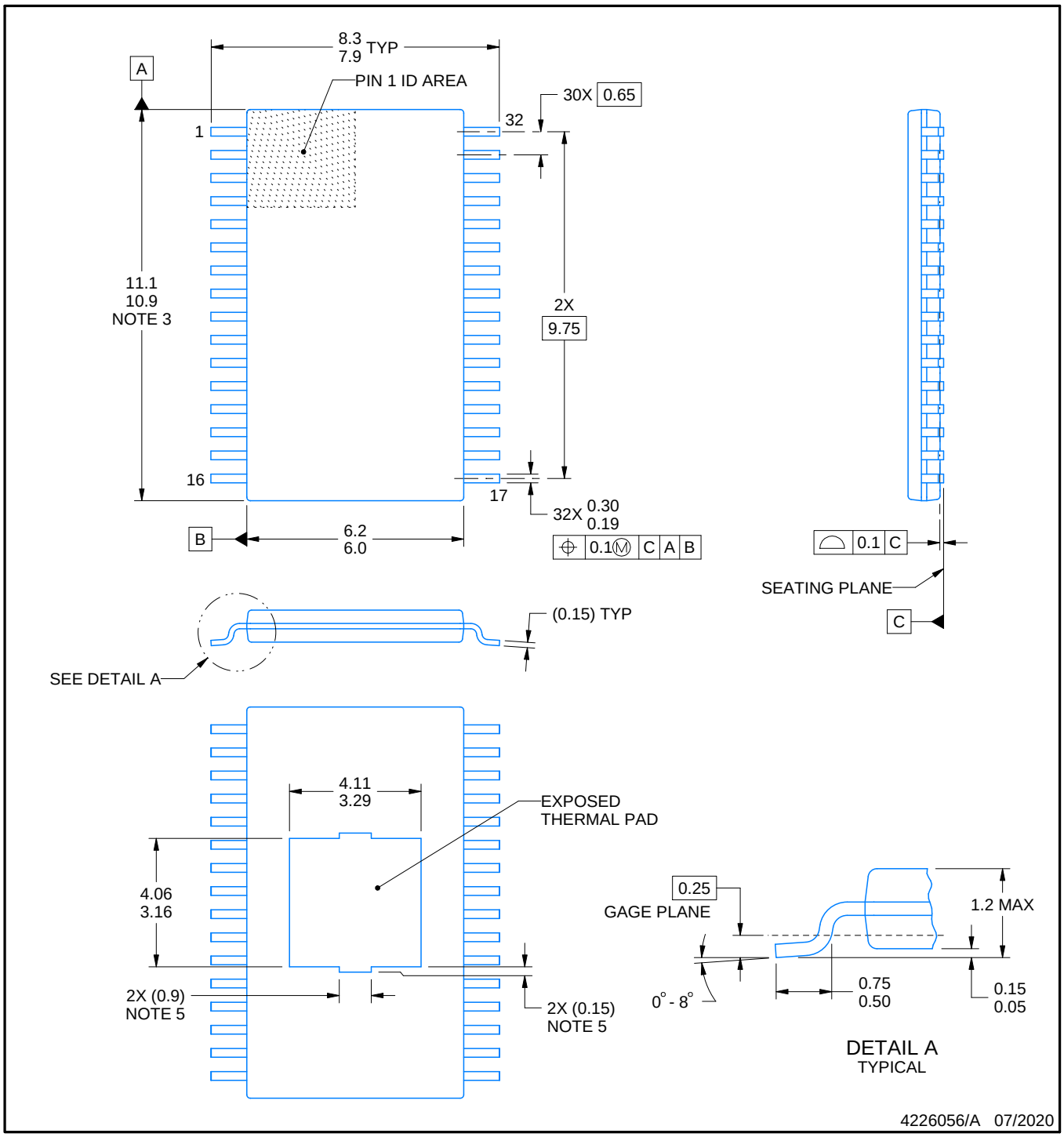


PACKAGE OUTLINE

DAP0032F

PowerPAD™ TSSOP - 1.2 mm max height

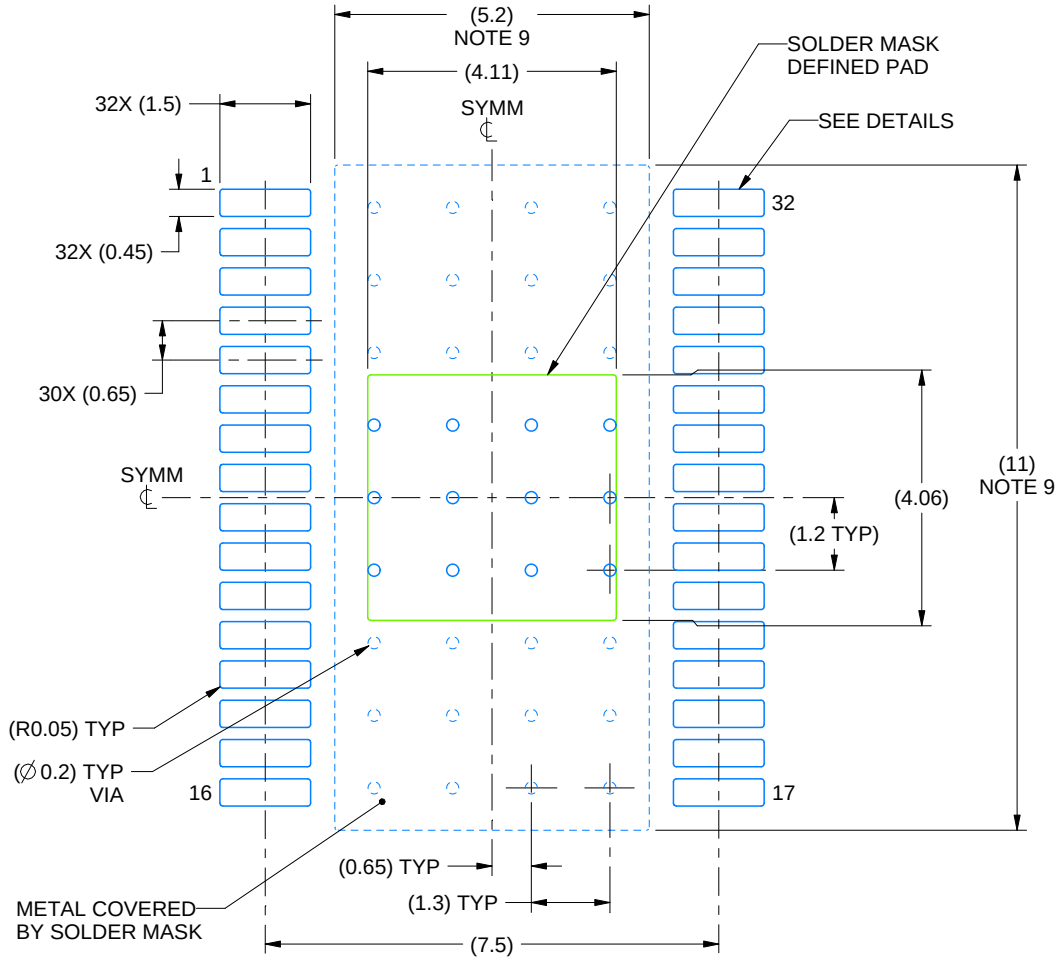
PLASTIC SMALL OUTLINE



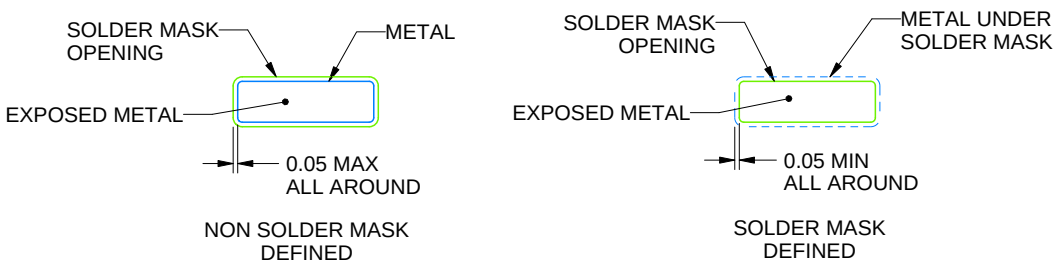
PowerPAD is a trademark of Texas Instruments.

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.
5. Features may differ and may not be present.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X

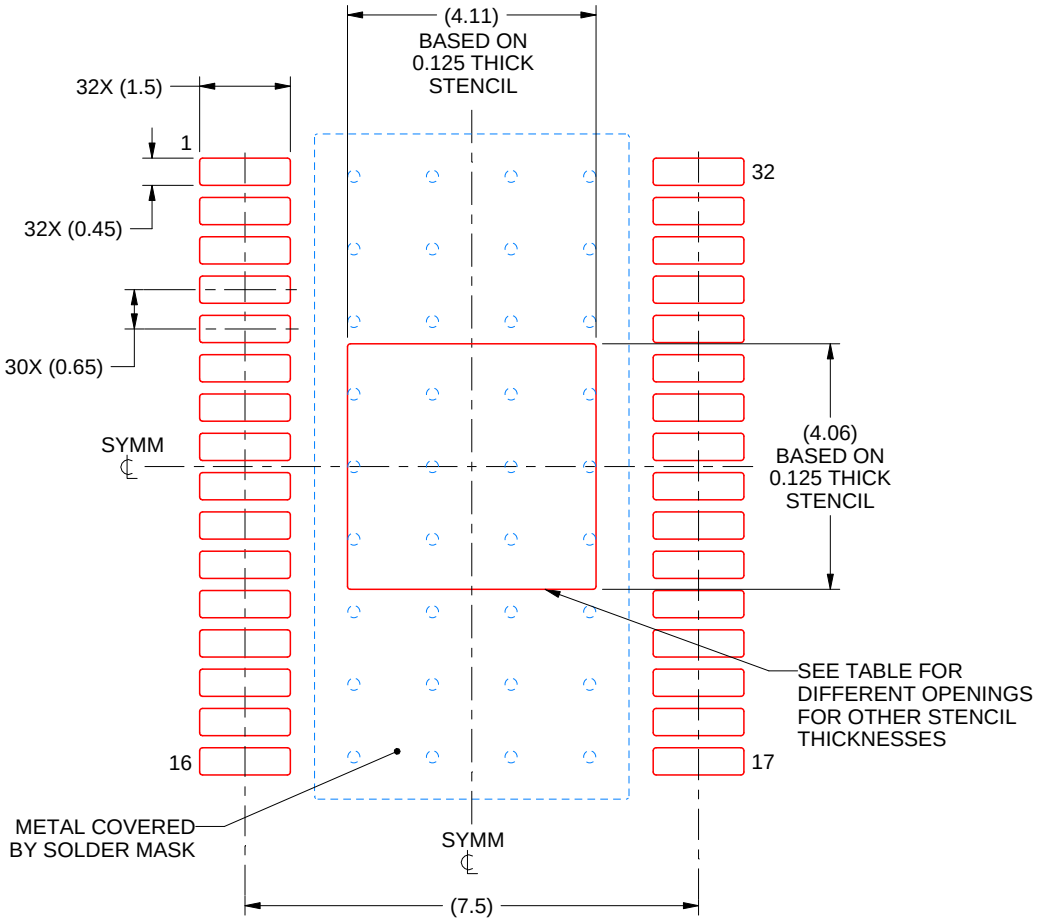


SOLDER MASK DETAILS
NOT TO SCALE

4226056/A 07/2020

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Size of metal pad may vary due to creepage requirement.



SOLDER PASTE EXAMPLE
EXPOSED PAD
100% PRINTED SOLDER COVERAGE BY AREA
SCALE:8X

STENCIL THICKNESS	SOLDER STENCIL OPENING
0.1	4.60 X 4.54
0.125	4.11 X 4.06 (SHOWN)
0.15	3.75 X 3.71
0.175	3.47 X 3.43

4226056/A 07/2020

NOTES: (continued)

10. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
11. Board assembly site may have different recommendations for stencil design.

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